



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Blaine J. Thurgood

Serial No.: 10/787,351

Filed: February 26, 2004

For: SEMICONDUCTOR DIE
CONFIGURED FOR USE WITH
INTERPOSER SUBSTRATES HAVING
REINFORCED INTERCONNECT SLOTS

Confirmation No.: 4866

Examiner: J. Clark

Group Art Unit: 2815

Attorney Docket No.: 2269-5520.2US
(02-0676.02/US)

Notice of Allowance Mailed:

January 6, 2006

NOTICE OF EXPRESS MAILING

Express Mail Mailing Label Number: EL995990041US

Date of Deposit with USPS: April 4, 2006

Person making Deposit: Timothy Palfreyman

OK to enter
jbc
04/17/06

AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)

Mail Stop ISSUE FEE
Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Sir:

Please amend the above-referenced application as follows: